

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCTS CHARACTERISTICS

I_{F(AV)}	2 x 8 A
V_{RRM}	45 V
T_j (max)	150 °C
V_F (max)	0.45 V

FEATURES AND BENEFITS

- LOW FORWARD VOLTAGE DROP MEANING VERY SMALL CONDUCTION LOSSES
- LOW SWITCHING LOSSES ALLOWING HIGH FREQUENCY OPERATION
- INSULATED PACKAGE: TO-220FPAB
Insulated voltage: 2000V DC
Capacitance: 12 pF
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Dual center tap Schottky barrier rectifier designed for high frequency Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in TO-220AB and TO-220FPAB, these devices are intended for use in low voltage, high frequency converters, free-wheeling and polarity protection applications.

ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter				Value	Unit	
V _{RRM}	Repetitive peak reverse voltage				45	V	
I _{F(RMS)}	RMS forward current				30	A	
I _{F(AV)}	Average forward current	TO-220AB	T _c = 140°C $\delta = 0.5$	Per diode	8	A	
				Per device	16		
		TO-220FPAB	T _c = 125°C $\delta = 0.5$	Per diode	8	A	
				Per device	16		
I _{FSM}	Surge non repetitive forward current	tp = 10 ms sinusoidal		180	A		
I _{RRM}	Repetitive peak reverse current	tp=2 µs square F=1kHz		1	A		
I _{RSM}	Non repetitive peak reverse current	tp = 100 µs square		2	A		
PARM	Repetitive peak avalanche power	tp = 1µs T _j = 25°C		4000	W		
T _{stg}	Storage temperature range	- 65 to + 150			°C		
T _j	Maximum operating junction temperature *	150			°C		
dV/dt	Critical rate of rise of reverse voltage	10000			V/µs		

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB	Per diode	2.2	$^{\circ}\text{C}/\text{W}$
			Total Coupling	1.3 0.3	
		TO-220FPAB	Per diode	4.5	$^{\circ}\text{C}/\text{W}$
			Total Coupling	3.5 2.5	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			0.2	mA
		$T_j = 125^{\circ}\text{C}$			65	130	mA
V_F *	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 8 \text{ A}$			0.5	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 8 \text{ A}$			0.39	
		$T_j = 25^{\circ}\text{C}$	$I_F = 16 \text{ A}$			0.63	
		$T_j = 125^{\circ}\text{C}$	$I_F = 16 \text{ A}$			0.55	

Pulse test : * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation :

$$P = 0.26 \times I_F(\text{AV}) + 0.024 I_F^2(\text{RMS})$$

Fig. 1: Average forward power dissipation versus average forward current (per diode).

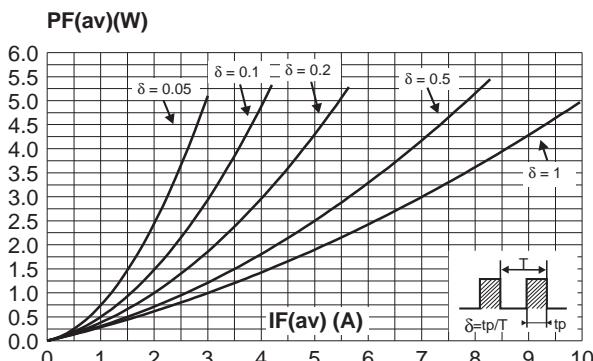


Fig. 3: Normalized avalanche power derating versus pulse duration.

Fig. 2: Average current versus ambient temperature ($\delta = 0.5$) (per diode).

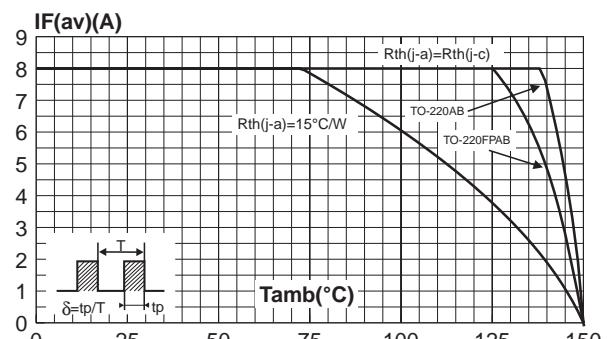


Fig. 4: Normalized avalanche power derating versus junction temperature.

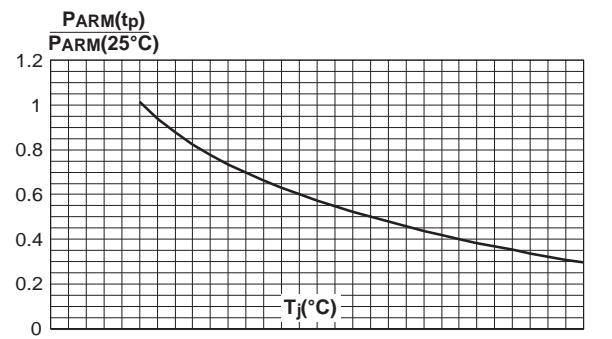


Fig. 5-1: Non repetitive surge peak forward current versus overload duration (maximum values per diode, TO-220AB).

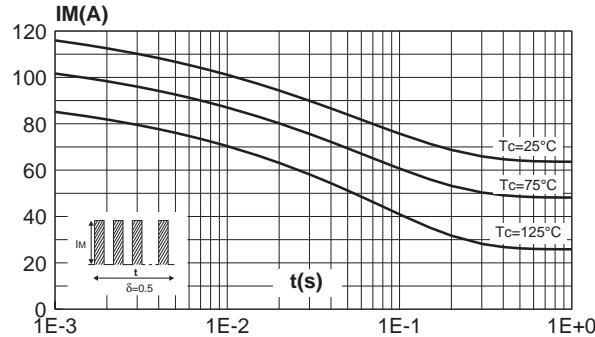


Fig. 5-2: Non repetitive surge peak forward current versus overload duration (maximum values per diode, TO-220FPAB).

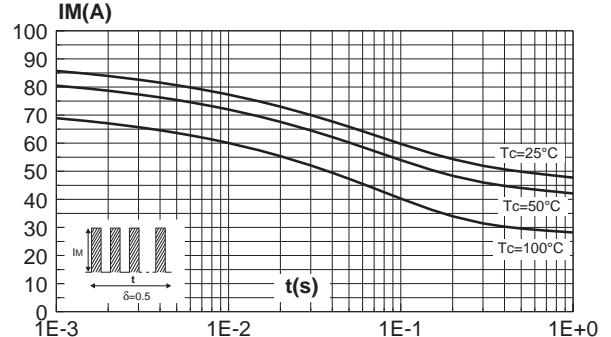


Fig. 6-1: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB).

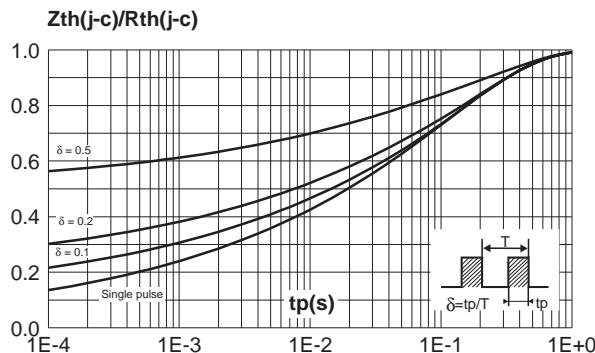


Fig. 6-2: Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB).

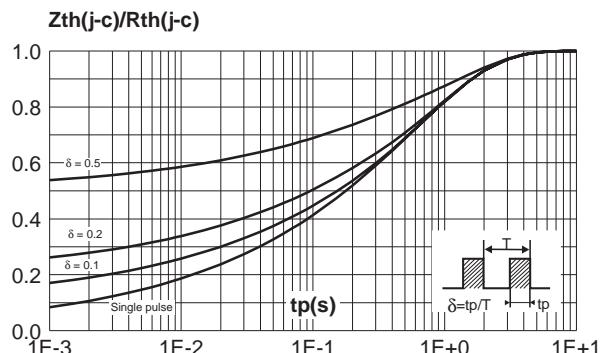


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values) (per diode).

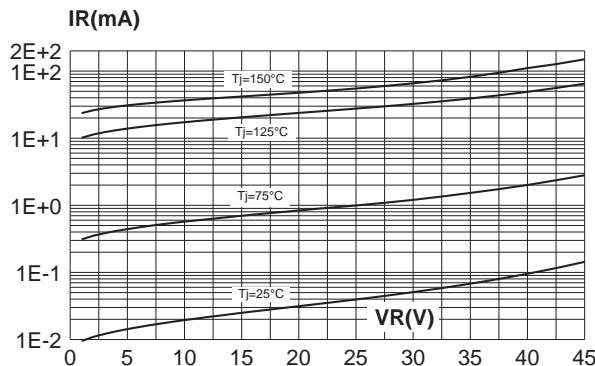
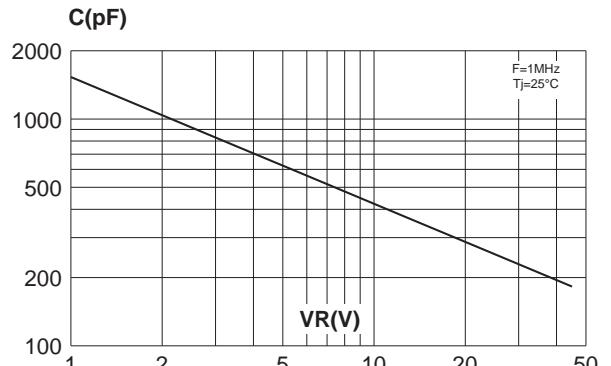
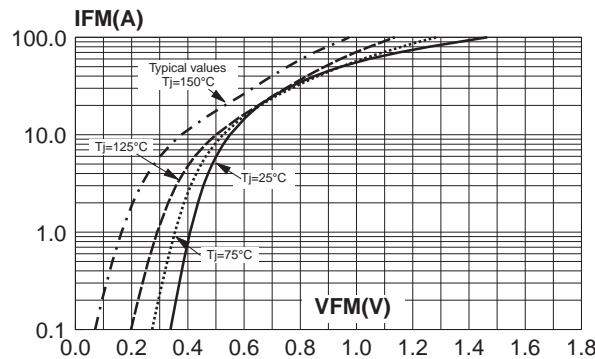


Fig. 8: Junction capacitance versus reverse voltage applied (typical values) (per diode).



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Fig. 9: Forward voltage drop versus forward current (maximum values) (per diode).



PACKAGE MECHANICAL DATA

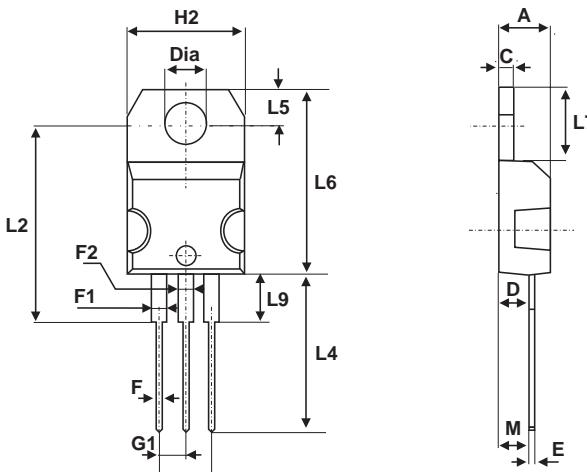
TO-220FPAB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

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PACKAGE MECHANICAL DATA

TO-220AB



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS16L45CT	STPS16L45CT	TO-220AB	2g	50	Tube
STPS16L45CFP	STPS16L45CFP	TO-220FPAB	2g	50	Tube

- Epoxy meets UL94,V0
- Cooling method : C
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

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